

ISL9V3040D3STV

ECOSPARK[®] Ignition IGBT

300 mJ, 400 V, N-Channel Ignition IGBT

Features

- SCIS Energy = 300 mJ at $T_J = 25^\circ\text{C}$
- Logic Level Gate Drive
- This Device is Pb-Free and is RoHS Compliant
- AEC-Q101 Qualified and PPAP Capable

Applications

- Automotive Ignition Coil Driver Circuits
- High Current Ignition System
- Coil on Plug Applications

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ Unless Otherwise Stated)

Parameter	Symbol	Value	Units
Collector to Emitter Breakdown Voltage ($I_C = 1\text{ mA}$)	BV_{CER}	400	V
Emitter to Collector Voltage – Reverse Battery Condition ($I_C = 10\text{ mA}$)	BV_{ECS}	24	V
ISCIS = 14.2 A, L = 3.0 mHz, $R_{GE} = 1\text{ K}\Omega$ (Note 1), $T_C = 25^\circ\text{C}$	E_{SCIS25}	300	mJ
ISCIS = 10.6 A, L = 3.0 mHz, $R_{GE} = 1\text{ K}\Omega$ (Note 2), $T_C = 150^\circ\text{C}$	$E_{SCIS150}$	170	mJ
Collector Current Continuous, at $V_{GE} = 4.0\text{ V}$, $T_C = 25^\circ\text{C}$	I_{C25}	21	A
Collector Current Continuous, at $V_{GE} = 4.0\text{ V}$, $T_C = 110^\circ\text{C}$	I_{C110}	17	A
Gate to Emitter Voltage Continuous	V_{GEM}	± 10	V
Power Dissipation Total, $T_C = 25^\circ\text{C}$	PD	150	W
Power Dissipation Derating, $T_C > 25^\circ\text{C}$	PD	1	W/ $^\circ\text{C}$
Operating Junction and Storage Temperature	T_J, T_{STG}	-55 to 175	$^\circ\text{C}$
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)	T_L	300	$^\circ\text{C}$
Reflow soldering according to JESD020C	T_{PKG}	260	$^\circ\text{C}$
HBM-Electrostatic Discharge Voltage at 100 pF, 1500 Ω	ESD	4	kV
CDM-Electrostatic Discharge Voltage at 1 Ω	ESD	2	kV

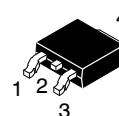
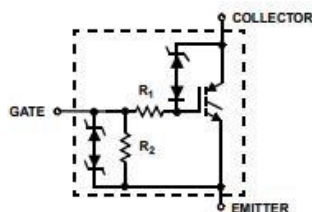
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Self Clamped inductive Switching Energy (E_{SCIS25}) of 300 mJ is based on the test conditions that is starting $T_J = 25^\circ\text{C}$, L = 3 mHz, ISCIS = 14.2 A, $V_{CC} = 100\text{ V}$ during inductor charging and $V_{CC} = 0\text{ V}$ during time in clamp.
2. Self Clamped inductive Switching Energy ($E_{SCIS150}$) of 170 mJ is based on the test conditions that is starting $T_J = 150^\circ\text{C}$, L = 3 mHz, ISCIS = 10.6 A, $V_{CC} = 100\text{ V}$ during inductor charging and $V_{CC} = 0\text{ V}$ during time in clamp.



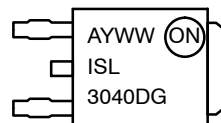
ON Semiconductor[®]

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DPAK (SINGLE GAUGE)
CASE 369C

MARKING DIAGRAM



ISL3040DG = Device Code
A = Assembly Location
Y = Year
WW = Work Week
G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

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THERMAL RESISTANCE RATINGS

Characteristic	Symbol	Max	Units
Junction-to-Case – Steady State (Drain) (Notes 1, 3 and 4)	$R_{\theta JC}$	1	°C/W

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ Unless Otherwise Specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Collector to Emitter Breakdown Voltage	BV_{CER}	$I_{CE} = 2\text{ mA}$, $V_{GE} = 0\text{ V}$, $R_{GE} = 1\text{ K}\Omega$, $T_J = -40\text{ to }150^\circ\text{C}$	370	400	430	V	
Collector to Emitter Breakdown Voltage	BV_{CES}	$I_{CE} = 10\text{ mA}$, $V_{GE} = 0\text{ V}$, $R_{GE} = 0$, $T_J = -40\text{ to }150^\circ\text{C}$	390	420	450	V	
Emitter to Collector Breakdown Voltage	BV_{ECS}	$I_{CE} = -75\text{ mA}$, $V_{GE} = 0\text{ V}$, $T_J = 25^\circ\text{C}$	30	–	–	V	
Gate to Emitter Breakdown Voltage	BV_{GES}	$I_{GES} = \pm 2\text{ mA}$	± 12	± 14	–	V	
Collector to Emitter Leakage Current	I_{CER}	$V_{CE} = 175\text{ V}$, $R_{GE} = 1\text{ K}\Omega$	$T_J = 25^\circ\text{C}$	–	–	25	μA
			$T_J = 150^\circ\text{C}$	–	–	1	mA
Emitter to Collector Leakage Current	I_{ECS}	$V_{EC} = 24\text{ V}$	$T_J = 25^\circ\text{C}$	–	–	1	mA
			$T_J = 150^\circ\text{C}$	–	–	40	
Series Gate Resistance	R_1		–	70	–	Ω	
Gate to Emitter Resistance	R_2		10 K	–	26 K	Ω	

ON CHARACTERISTICS

Collector to Emitter Saturation Voltage	$V_{CE(SAT)}$	$I_{CE} = 6\text{ A}$, $V_{GE} = 4\text{ V}$, $T_J = 25^\circ\text{C}$	–	1.25	1.65	V
Collector to Emitter Saturation Voltage	$V_{CE(SAT)}$	$I_{CE} = 10\text{ A}$, $V_{GE} = 4.5\text{ V}$, $T_J = 150^\circ\text{C}$	–	1.58	1.80	V
Collector to Emitter Saturation Voltage	$V_{CE(SAT)}$	$I_{CE} = 15\text{ A}$, $V_{GE} = 4.5\text{ V}$, $T_J = 150^\circ\text{C}$	–	1.90	2.20	V

DYNAMIC CHARACTERISTICS

Gate Charge	$Q_{G(ON)}$	$I_{CE} = 10\text{ A}$, $V_{CE} = 12\text{ V}$, $V_{GE} = 5\text{ V}$	–	17	–	nC	
Gate to Emitter Threshold Voltage	$V_{GE(TH)}$	$I_{CE} = 1\text{ mA}$, $V_{CE} = V_{GE}$	$T_J = 25^\circ\text{C}$	1.3	–	2.2	V
			$T_J = 150^\circ\text{C}$	0.75	–	1.8	
Gate to Emitter Plateau Voltage	V_{GEP}	$V_{CE} = 12\text{ V}$, $I_{CE} = 10\text{ A}$	–	3.0	–	V	

SWITCHING CHARACTERISTICS

Current Turn-On Delay Time-Resistive	$t_{d(ON)R}$	$V_{CE} = 14\text{ V}$, $R_L = 1\text{ }\Omega$, $V_{GE} = 5\text{ V}$, $R_G = 470\text{ }\Omega$, $T_J = 25^\circ\text{C}$	–	0.7	4	μs
Current Rise Time-Resistive	t_{rR}		–	2.1	7	
Current Turn-Off Delay Time-Inductive	$t_{d(OFF)L}$	$V_{CE} = 300\text{ V}$, $L = 1\text{ mH}$, $V_{GE} = 5\text{ V}$, $R_G = 470\text{ }\Omega$, $I_{CE} = 6.5\text{ A}$, $T_J = 25^\circ\text{C}$	–	4.8	15	
Current Fall Time-Inductive	t_{fL}		–	2.8	15	

PACKAGE MARKING AND ORDERING INFORMATION

Device Marking	Device	Package	Reel Diameter	Tape Width	Qty
ISL9V3040G1	ISL9V3040D3STV	DPAK (Pb-Free)	330 mm	16 mm	2500

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ISL9V3040D3STV

TYPICAL CHARACTERISTICS

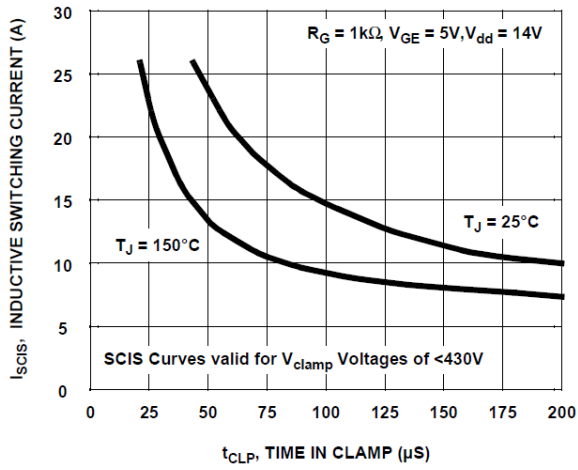


Figure 1. Self Clamped Inductive Switching Current vs. Time in Clamp

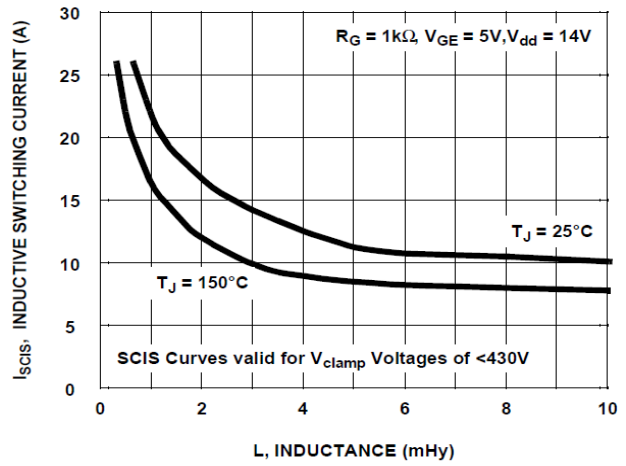


Figure 2. Self Clamped Inductive Switching Current vs. Inductance

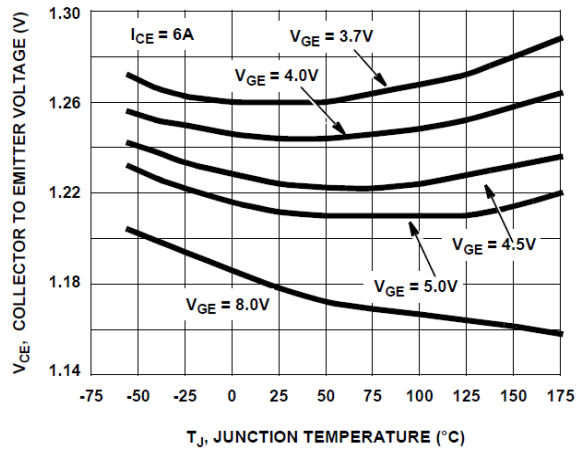


Figure 3. Collector to Emitter On-State Voltage vs. Junction Temperature

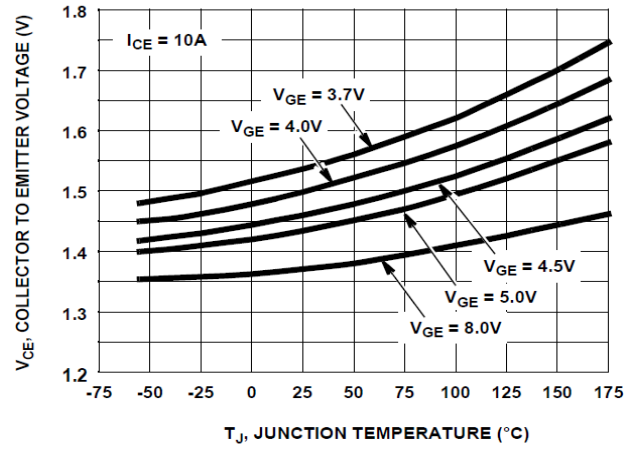


Figure 4. Collector to Emitter On-State Voltage vs. Junction Temperature

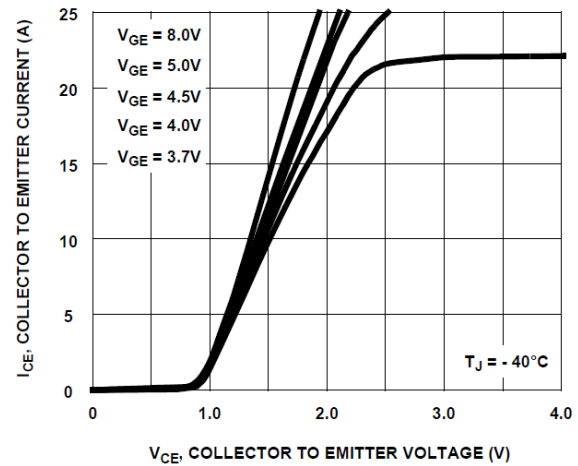


Figure 5. Collector to Emitter On-State Voltage vs. Collector Current

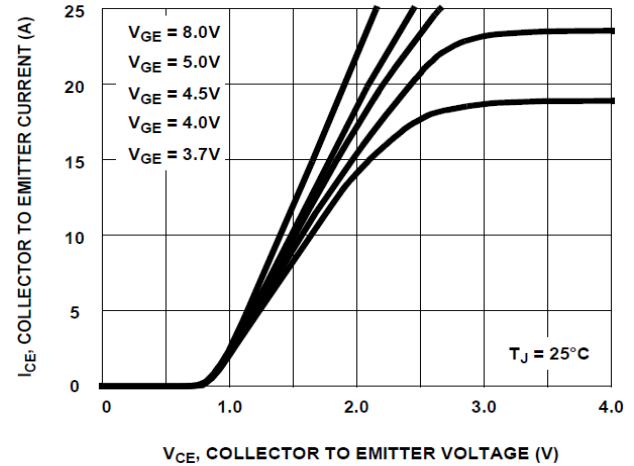


Figure 6. Collector to Emitter On- State Voltage vs. Collector Current

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TYPICAL CHARACTERISTICS (continued)

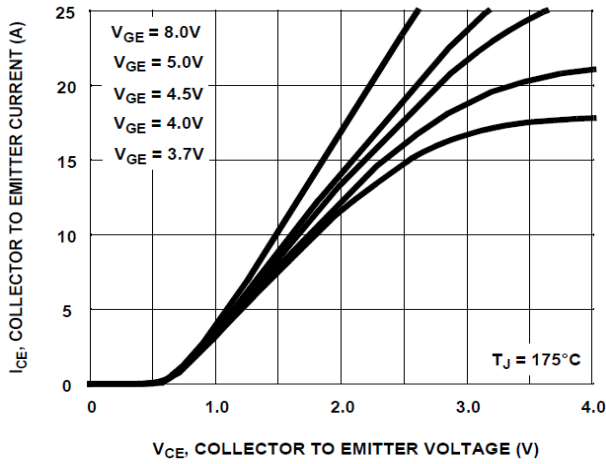


Figure 7. Collector to Emitter On-State Voltage vs. Collector Current

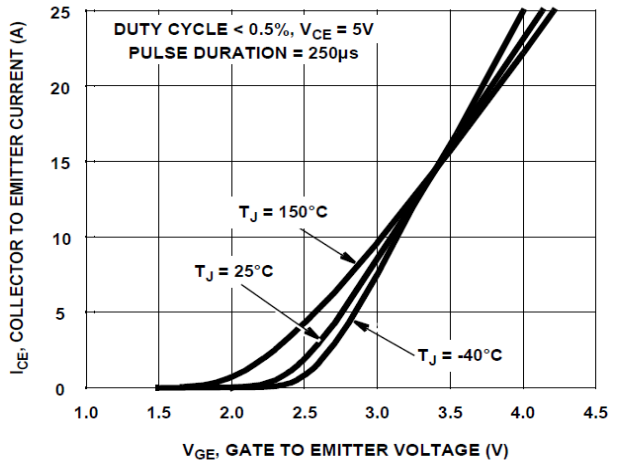


Figure 8. Transfer Characteristics

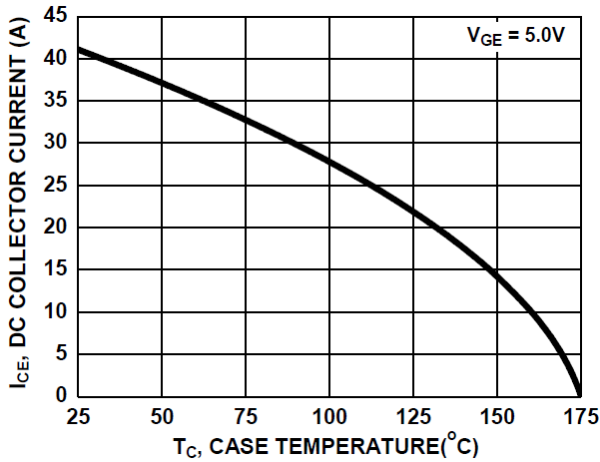


Figure 9. DC Collector Current vs. Case Temperature

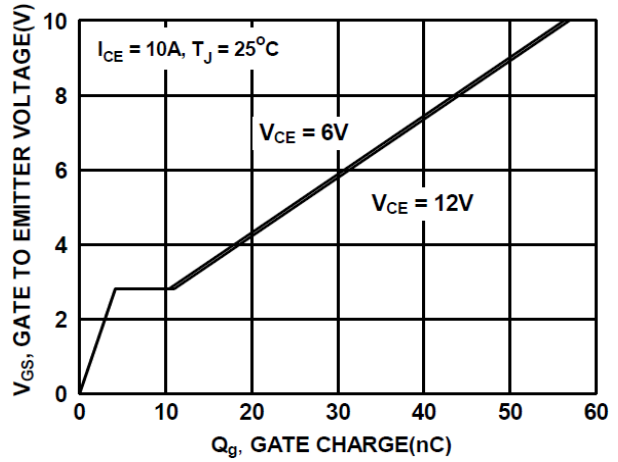


Figure 10. Gate Charge

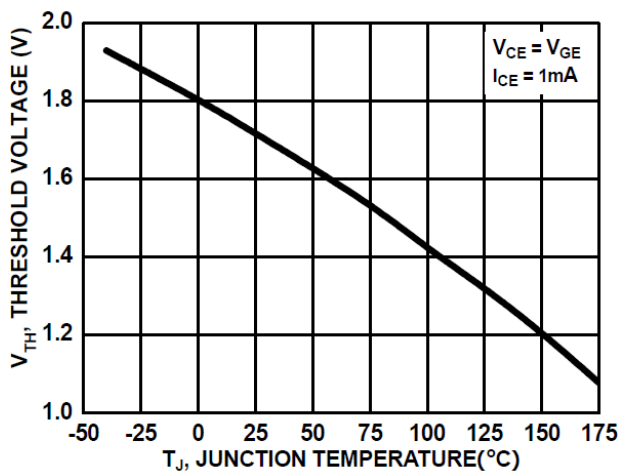


Figure 11. Threshold Voltage vs. Junction Temperature

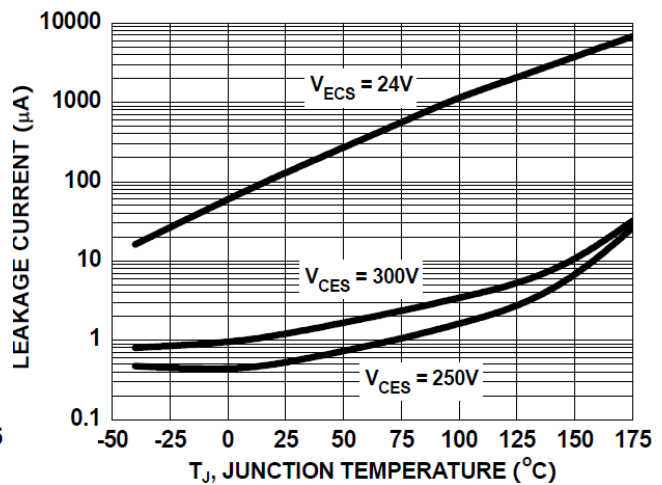


Figure 12. Leakage Current vs. Junction Temperature

ISL9V3040D3STV

TYPICAL CHARACTERISTICS (continued)

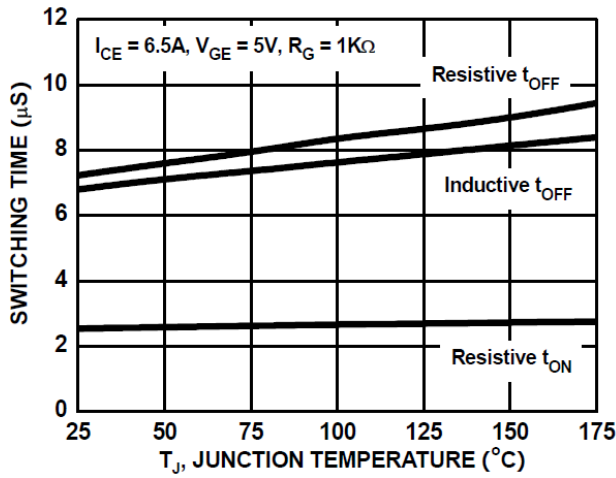


Figure 13. Switching Time vs. Junction Temperature

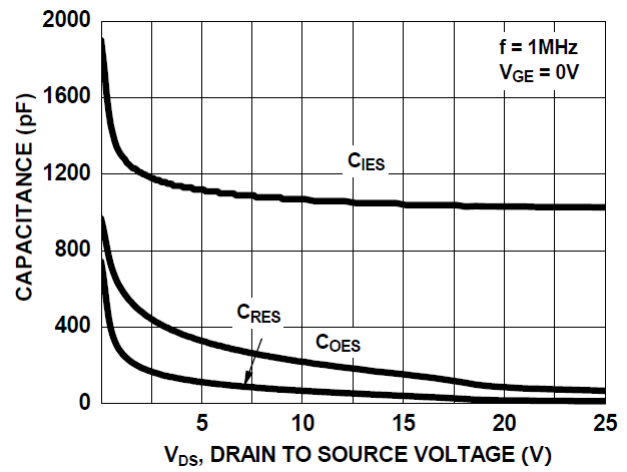


Figure 14. Capacitance vs. Collector to Emitter Voltage

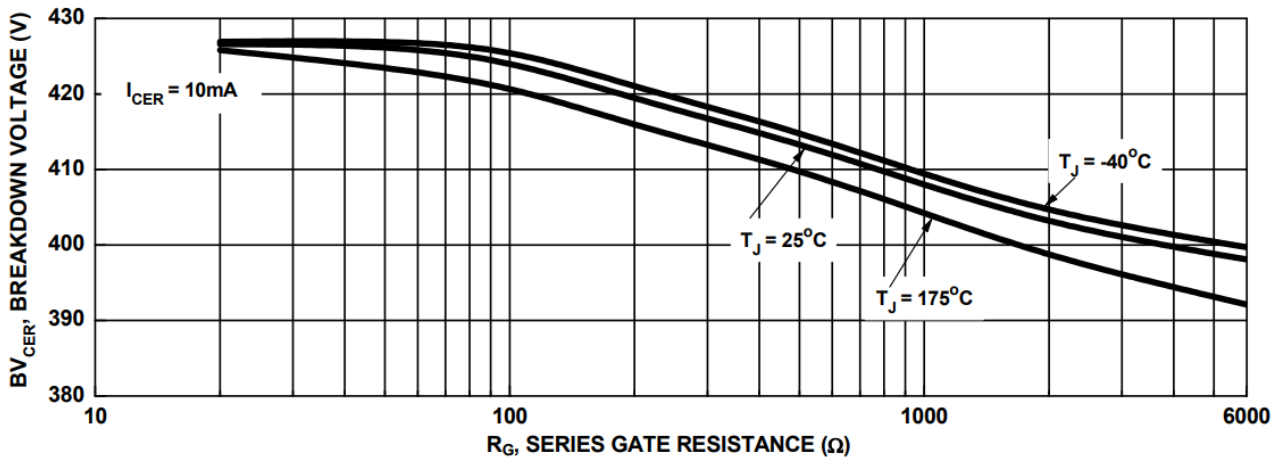


Figure 15. Break down Voltage vs. Series Resistance

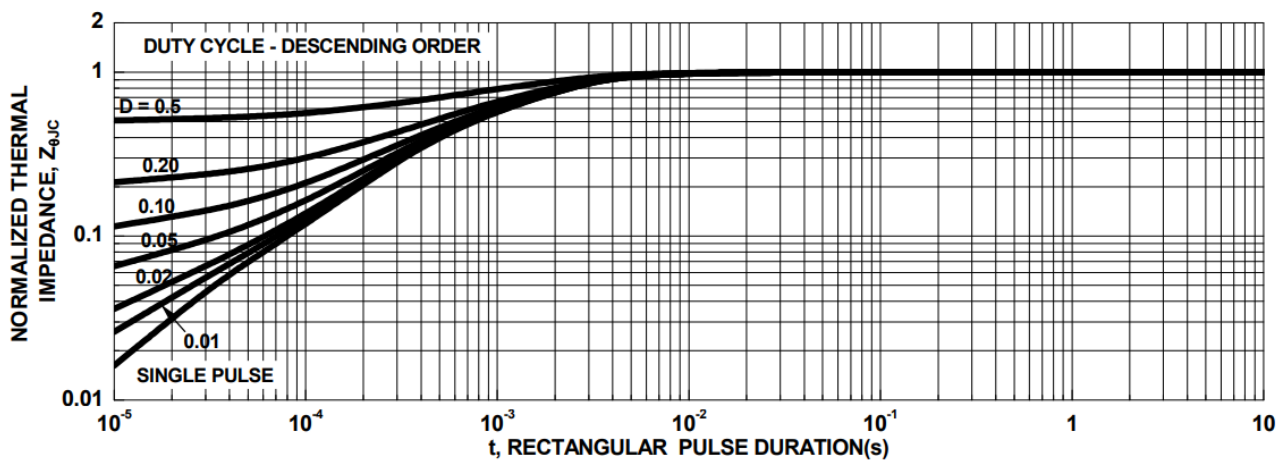


Figure 16. IGBT Normalized Transient Thermal Impedance, Junction to Case

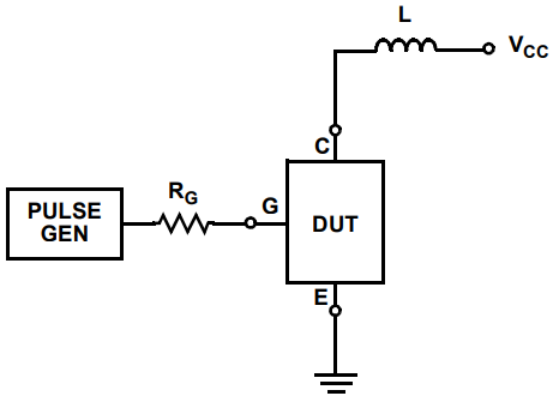


Figure 17. Inductive Switching Test Circuit

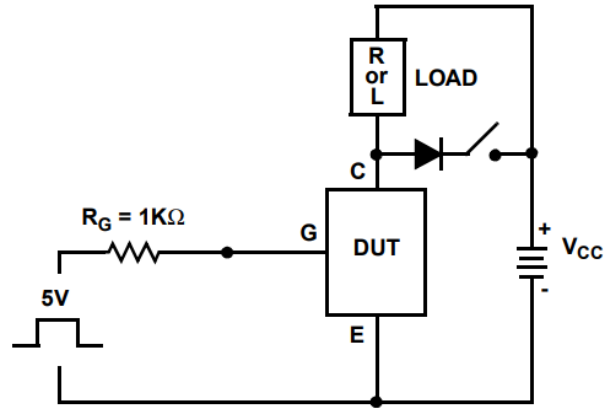


Figure 18. t_{ON} and t_{OFF} Switching Test Circuit

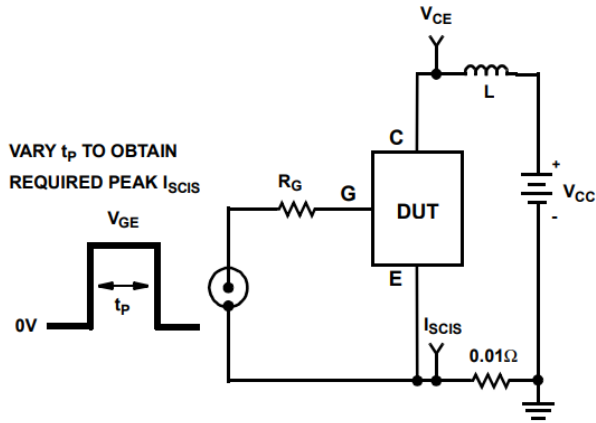


Figure 19. Energy Test Circuit

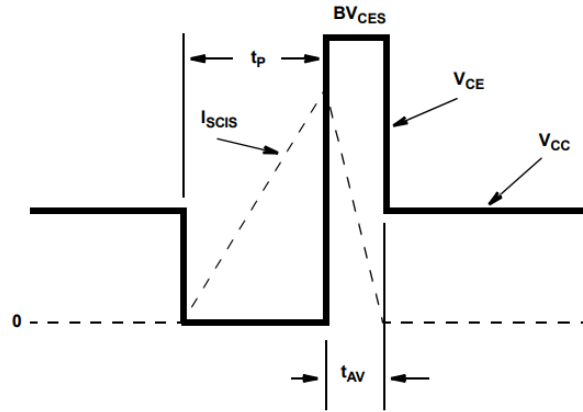
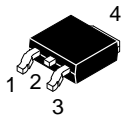


Figure 20. Energy Waveforms

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

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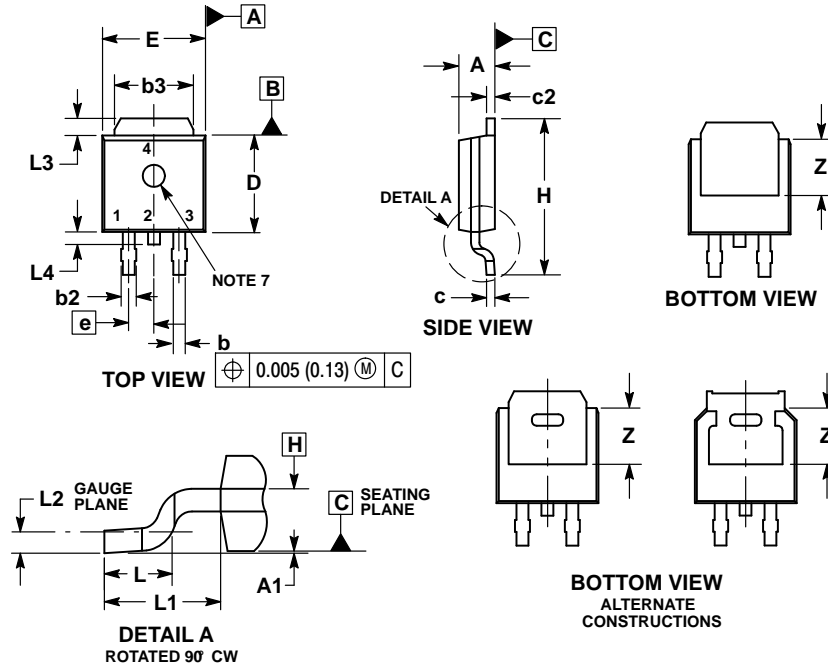
SCALE 1:1

DPAK (SINGLE GAUGE)

CASE 369C

ISSUE F

DATE 21 JUL 2015

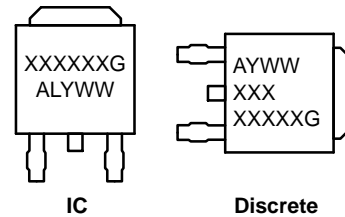


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
7. OPTIONAL MOLD FEATURE.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.028	0.045	0.72	1.14
b3	0.180	0.215	4.57	5.46
c	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
e	0.090 BSC		2.29 BSC	
H	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.114 REF		2.90 REF	
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4	---	0.040	---	1.01
Z	0.155	---	3.93	---

GENERIC MARKING DIAGRAM*

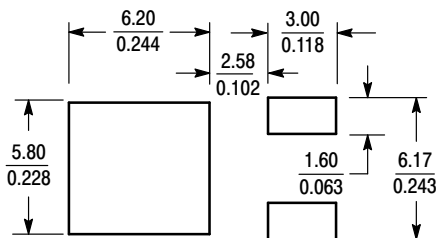


- XXXXXX = Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking.

- | | | | | |
|--|--|---|---|--|
| <p>STYLE 1:
PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR</p> | <p>STYLE 2:
PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN</p> | <p>STYLE 3:
PIN 1. ANODE
2. CATHODE
3. ANODE
4. CATHODE</p> | <p>STYLE 4:
PIN 1. CATHODE
2. ANODE
3. GATE
4. ANODE</p> | <p>STYLE 5:
PIN 1. GATE
2. ANODE
3. CATHODE
4. ANODE</p> |
| <p>STYLE 6:
PIN 1. MT1
2. MT2
3. GATE
4. MT2</p> | <p>STYLE 7:
PIN 1. GATE
2. COLLECTOR
3. EMITTER
4. COLLECTOR</p> | <p>STYLE 8:
PIN 1. N/C
2. CATHODE
3. ANODE
4. CATHODE</p> | <p>STYLE 9:
PIN 1. ANODE
2. CATHODE
3. RESISTOR ADJUST
4. CATHODE</p> | <p>STYLE 10:
PIN 1. CATHODE
2. ANODE
3. CATHODE
4. ANODE</p> |

SOLDERING FOOTPRINT*




SCALE 3:1 (mm / inches)

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:	REF TO JEDEC TO-252	
DESCRIPTION:	DPAK SINGLE GAUGE SURFACE MOUNT	PAGE 1 OF 2



ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ. BY L. GAN	24 SEP 2001
A	ADDED STYLE 8. REQ. BY S. ALLEN.	06 AUG 2008
B	ADDED STYLE 9. REQ. BY D. WARNER.	16 JAN 2009
C	ADDED STYLE 10. REQ. BY S. ALLEN.	09 JUN 2009
D	RELABELED DRAWING TO JEDEC STANDARDS. ADDED SIDE VIEW DETAIL A. CORRECTED MARKING INFORMATION. REQ. BY D. TRUHITE.	29 JUN 2010
E	ADDED ALTERNATE CONSTRUCTION BOTTOM VIEW. MODIFIED DIMENSIONS b2 AND L1. CORRECTED MARKING DIAGRAM FOR DISCRETE. REQ. BY I. CAMBALIZA.	06 FEB 2014
F	ADDED SECOND ALTERNATE CONSTRUCTION BOTTOM VIEW. REQ. BY K. MUSTAFA.	21 JUL 2015

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Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

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